

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

MICRON TECHNOLOGY, INC.,
MICRON SEMICONDUCTOR PRODUCTS, INC., and
MICRON TECHNOLOGY TEXAS, LLC,
Petitioner

v.

BESANG INC.,
Patent Owner.

Case No. IPR2023-00900
U.S. Patent No. 7,378,702

PETITIONER'S UPDATED LIST OF EXHIBITS

UPDATED LIST OF EXHIBITS¹

Ex-1001	U.S. Patent No. 7,378,702 (“the ’702 Patent”)
Ex-1002	Declaration of Dr. Jack C. Lee
Ex-1003	Curriculum Vitae of Dr. Jack C. Lee
Ex-1004	Prosecution History of U.S. Patent No. 7,378,702 (App. No. 10/934,270)
Ex-1005	U.S. Patent No. 5,091,762 (“Watanabe”)
Ex-1006	U.S. Patent Application Pub. No. US2002/0154556 (“Endoh”)
Ex-1007	U.S. Patent No. 6,881,994 (“Lee”)
Ex-1008	U.S. Patent No. 7,221,008 (“Matamis”)
Ex-1009	G. Groeseneken et al., <i>Basics of Nonvolatile Semiconductor Memory Devices</i> , in <i>Nonvolatile Semiconductor Memory Technology: A Comprehensive Guide to Understanding and Using NVSM Devices</i> (William D. Brown & Joe Brewer eds., 1997)
Ex-1010	Philip M. Sailer et al., <i>Creating 3D Circuits Using Transferred Films</i> , IEEE Circuits & Devices (1997)
Ex-1011	U.S. Patent No. 5,808,938 (“Tran”)
Ex-1012	U.S. Patent No. 6,982,905 (“Nguyen”)
Ex-1013	U.S. Patent No. 6,807,098 (“Jeong”)
Ex-1014	Kee-Ho Yu et al., <i>Real-Time Microvision System with Three-Dimensional Integration Structure</i> , IEEE Int’l Conference on Multisensor Fusion and Integration for Intelligent Sys. (1996)
Ex-1015	U.S. Patent No. 5,374,564 (“Bruel”)
Ex-1016	Horacio Mendez, <i>Silicon-on-Insulator: SOI Technology and Ecosystem – Emerging SOI Applications</i> , SOI Indus. Consortium (2009)
Ex-1017	U.S. District Courts – Combined Civil and Criminal Federal Court Management Statistics (Dec. 31, 2022), available at: https://www.uscourts.gov/statistics-reports/federal-court-management-statistics-december-2022
Ex-1018	T. Mikolajick et al., <i>The Future of Charge Trapping Memories</i> , 2007 IEEE Int’l Symposium on VLSI Tech., Sys. & Applications (2007)
Ex-1019	Complaint, <i>BeSang Inc. v. Micron Tech., Inc.</i> , No. 2:23-cv-00028

¹ Four-digit pin citations that begin with 0 are the page stamps added by Micron in the bottom right corner of the exhibits. All other pin citations are to original page, column, paragraph, or line numbers.

	(E.D. Tex. Jan. 23, 2023)
Ex-1020	Jim Handy, <i>3D NAND: Benefits of Charge Traps over Floating Gates</i> , The Memory Guy Blog (Nov. 22, 2013)
Ex-1021	E. Bertagnolli et al., <i>ROS: An Extremely High Density MASK ROM Technology Based on Vertical Transistor Cells</i> , IEEE (1996)
Ex-1022	Tetsuo Endoh et al., <i>Novel Ultrahigh-Density Flash memory with A Stacked-Surrounding Gate Transistor (S-SGT) Structured Cell</i> , 50 IEEE Transactions on Electron Devices 945 (2003)
Ex-1023	F. Nemati & J.D. Plummer, <i>A Novel High Density, Low Voltage SRAM Cell with A Vertical NDR Device</i> , IEEE (1998)
Ex-1024	K.W. Lee et al., <i>Three-Dimensional Shared Memory Fabricated Using Wafer Stacking Technology</i> , IEEE (2000)
Ex-1025	<i>NAND vs. NOR Flash Memory</i> , Toshiba America Electronic Components, Inc. (2006)
Ex-1026	G.K. Celler & Sorin Crisoloveanu, <i>Frontiers of Silicon-on-Insulator</i> , 93 J. Applied Physics 4955 (2003)
Ex-1027	Timeline, Soitec, available at: https://www.soitec.com/en/company/soitec-activity/history (last visited Apr. 25, 2023)
Ex-1028	G. Shahidi et al., <i>Fabrication of CMOS on Ultrathin SOI Obtained by Epitaxial Lateral Overgrowth and Chemical-Mechanical Polishing</i> , IEEE (1991)
Ex-1029	MicroChemicals, Further Processing of Silicon Wafers: SiO_2 , Si_3N_4 , Metallization, Epitaxy and Dicing, available at: https://www.microchemicals.com/technical_information/silicon_wafer_sio2_si3n4_metallization_epitaxy_soi.pdf (last visited Apr. 28, 2023)
Ex-1030	Hiroshi Sakuraba et al., <i>New Three-Dimensional High-Density Stacked-Surrounding Gate Transistor (S-SGT) Flash Memory Architecture Using Self-Aligned Interconnection Fabrication Technology Without Photolithography Process for Tera-Bits and Beyond</i> , 43 Japanese J. Applied Physics 2217 (2004)
Ex-1031	Letter dated September 21, 2023 to counsel for Patent Owner from John Kappos
Ex-1032	<i>BeSang, Inc. v. Micron Technology Inc. et al.</i> , 2:23-CV-00028-JRG-RSP, D.I. 95 (E.D. Tex. Dec. 20, 2023), Order Granting Stipulation and Joint Motion to Stay Pending <i>Inter Partes</i> Review (“Order Granting Stay”)

Dated: December 27, 2023

Respectfully submitted,

/s/ John Kappos

John Kappos (Reg. No. 37,861)
O'Melveny & Myers LLP
2501 North Harwood Street, Suite 1700
Dallas, TX 75201
Telephone: (972) 360-1900
Fax: (972) 360-1901
E-Mail: jkappos@omm.com
Attorney for Petitioner

CERTIFICATE OF SERVICE

The undersigned hereby certifies that on December 27, 2023, the foregoing
PETITIONER'S UPDATED LIST OF EXHIBITS was served via electronic
mail, in its entirety, on Patent Owner's attorneys of record in IPR2023-00900.

Michelle E. Armond
michelle.armond@armondwilson.com
Joseph Li
josepher.li@armondwilson.com
Yue Han
amy.han@armondwilson.com
ARMOND WILSON LLP
4685 MacArthur Court, Suite 390
Newport Beach, CA 92660
Douglas R. Wilson
doug.wilson@armondwilson.com
ARMOND WILSON LLP
13785 Research Blvd., Suite 125
Austin, TX 78750

Dated: December 27, 2023

Respectfully submitted,

/s/ John Kappos

John Kappos (Reg. No. 37,861)
O'Melveny & Myers LLP
2501 North Harwood Street, Suite 1700
Dallas, TX 75201
Telephone: (972) 360-1900
Fax: (972) 360-1901
E-Mail: jkappos@omm.com
Attorney for Petitioner